

**PCN#20240329000.1**  
**Qualification of Clark as an additional Assembly site for select devices**  
**Change Notification / Sample Request**

**Date:** March 29, 2024

**To:** Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team  
SC Business Services

**20240329000.1**

**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TPS552882RPMR	NULL
TPS55288RPMR	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20240329000.1			<b>PCN Date:</b>	March 29, 2024
<b>Title:</b>	Qualification of Clark as an additional Assembly site for select devices				
<b>Customer Contact:</b>		Change Management team		<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>		June 27, 2024		<b>Sample Requests accepted until:</b>	April 28, 2024*
<b>*Sample requests received after April 28, 2024 will not be supported.</b>					
<b>Change Type:</b>					
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material	
<input type="checkbox"/> Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material	
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process	
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments Incorporated is announcing the qualification of Clark as an additional Assembly site for set of devices listed below. There are no construction differences between the 2 sites.					
<b>Reason for Change:</b>					
Supply continuity					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Impact on Environmental Ratings</b>					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>		
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change		
<b>Changes to product identification resulting from this PCN:</b>					
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>		
CDAT	CDA	CHN	Chengdu		
<b>Clark</b>	<b>QAB</b>	<b>PHL</b>	<b>Angeles City, Pampanga</b>		
Sample product shipping label (not actual product label)					
 <b>TEXAS INSTRUMENTS</b> MADE IN: Malaysia 2DC: 20: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 <b>LBL: 5A (L)T0:1750</b>	 G4		<p>(1P) <b>SN74LS07NSR</b>  (Q) <b>2000</b> (D) <b>0336</b>  (31T) <b>LOT: 3959047MLA</b>  (4W) <b>TKY(1T) 7523483SI2</b>  (P)  (2P) <b>REV: (V) 0033317</b>  (20L) <b>CSO: SHE (21L) CCO:USA</b>  (22L) <b>ASO:MLA (23L) ACO:MYS</b> </p>		
<b>Product Affected:</b>					

TPS552882RPMR	TPS55288RPMR
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TI Information  
Selective Disclosure

### Qualification Report

**TPS55288xRPMR**  
**Approve Date 27-March-2024**

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device:	Qual Device:	Process QBS Reference:	Package/Product QBS Reference:	Package QBS Reference:
					<u>TPS552882RPMR</u>	<u>TPS55288RPMR</u>	<u>TPS61378QWRTERQ1</u>	<u>TPS552882QRPMRQ1</u>	<u>TPS552882QRPMRQ1</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1/45/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0	3/231/0	-
HTOL	B1	Life Test	150C	408 Hours	-	-	3/231/0	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	1/800/0	-

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">TPS552882RPMR</a>	Qual Device: <a href="#">TPS55288RPMR</a>	Process QBS Reference: <a href="#">TPS61378QWRTERQ1</a>	Package/Product QBS Reference: <a href="#">TPS552882QRPMRQ1</a>	Package QBS Reference: <a href="#">TPS552882QRPMRQ1</a>
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	-	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	3/90/0	3/90/0	3/90/0
FTY	E6	Final Test Yield	-	-	1/AII/0	1/AII/0	-	-	1/AII/0

- QBS: Qual By Similarity
- Qual Device TPS552882RPMR is qualified at MSL2 260C
- Qual Device TPS55288RPMR is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2305-017

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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